

Ceramic Board Properties

INDEX	HP GRADE (Low Density)	HP GRADE (High Density)	HZ GRADE
Temperature	2300°F	2300°F	2600°F
Working Temp.	2100°F	2100°F	2462°F
Melting Point	3200°F	3200°F	3300°F
Color	Off White	Off White	Off White
Available Density (kg/m ³) (lbs/ft ³)	260-290 16-18	350-400 22-25	360-380 20-22
LOI(% by WT)	6 - 7%	6 - 7%	6 - 7%
Dielectric Strength	25.4 volts/mil	25.4 volts/mil	25.4 volts/mil
Shrinkage (%) 24 Hrs at temp. °F	-3 (2012°F)	-3 (2012°F)	-3 (2462°F)
Thermal Conductivity @ 400 °C (752°F) @ 800 °C (1472°F) @ 1000 °C (1832°F)	w/m-k (Btu in./hr/ft ² °F) 0.085 (.589) 0.132 (.915) 0.180 (1.25)	0.095 0.154 0.200 0.085 (.659) 0.132 (1.07) 0.180 (1.39)	0.092 0.143 0.185 0.085 (.638) 0.132 (.991) 0.180 (1.28)
Tensile (Mpa)	0.5 (psi)	0.5 (psi)	0.5 (psi)
Chem Analysis			
Al ₂ O ₃	47-49	47-49	39-40
SiO ₂	50-52	50-52	42-45
ZrO ₂	--	--	15-17
Fe ₂ O ₃	0.2	0.2	0.2
Na ₂ K ₂ O	<0.5	1/4", 1/2", 1", 1.5", 2"	0.2
Sizes Available Thickness	24"x36; 24x48 1/2, 1", 1.5", 2"	24x36"; 24x48" 1/4", 1/2", 1", 1.5", 2"	24"x36; 24"x48" 1", 1.5", 2"